# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

**Marketing Name / Model**  
[List multiple models if applicable.]

**HP Pavilion 32 QHD Display**

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm I/F Board<em>1, Control Board</em>1, LED Board*1, LED Driver Board</td>
<td>4</td>
</tr>
<tr>
<td>Batteries, excluding Li-ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
</tbody>
</table>
| **Li-ion batteries. Include all Li-ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)** | Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain.  
NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2. | 0                                     |
| Mercury-containing components                                                    | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0                                     |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm              | Includes background illuminated displays with gas discharge lamps panel*1 | 1                                     |
| Cathode Ray Tubes (CRT)                                                          |                                                                      | 0                                     |
| Capacitors / condensers (Containing PCB/PCT)                                     |                                                                      | 0                                     |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | C1 in adapter                                                        | 1                                     |
| External electrical cables and cords                                             | HDMI cable*1, Power cord*1, Adapter*1                                 | 3                                     |
| Gas Discharge Lamps                                                              |                                                                      | 0                                     |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs) |                                                                      | 0                                     |

HPI instructions for this template are available at [EL-MF877-01](EL-MF877-01)
### Item Description | Notes | Quantity of items included in product
--- | --- | ---
already listed as a separate item above) | | |
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |
Components and waste containing asbestos | | 0 |
Components, parts and materials containing refractory ceramic fibers | | 0 |
Components, parts and materials containing radioactive substances | | 0 |

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>2</td>
</tr>
<tr>
<td>Slothead screwdriver</td>
<td>1</td>
</tr>
<tr>
<td>Allen screwdriver</td>
<td>1</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove the rubber and screw on the column and hinge, then pull out the stand form the monitor head.
2. Separate the RC form the monitor head through the tear down slots which on the bottom side.
3. Unlock the back light wire*2 and LVDS*2 from the panel.
4. Remove the adhesive tape on the bucket and remove the back light wires from the LED driver board.
5. Remove screws *12 on the chassis and bucket.
6. Disconnect the FFC from the connector. And separate the CTRL BD from the holder by hand.
7. Unlock 5 screws on the chassis and PCBA. And separate PCBAs from the chassis.
8. Disconnect the wire from the interface board.
9. Disconnect the LVDS from the interface board.
10. Release the screws on the hinge and bucket.
11. Remove the hinge POM
12. Tear the rubber foot from base
13. Separate the base plate and base cover.

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3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Remove the rubber and use the allen screwdriver to unlock the column and hinge, then pull out the stand form the monitor head.

2. Separate the RC form the monitor head through the tear down slots which on the bottom side.
3. Unlock the back light wire*2 and LVDS*2 from the panel.

4. Remove the adhesive tape on the bucket and remove the back light wires from the LED driver board.

5. Remove screws *12 on the chassis and bucket.

HPI instructions for this template are available at [EL-MF877-01](EL-MF877-01).
6. Disconnect the FFC from the connector. And separate the CTRL BD from the holder by hand.

7. Unlock 5 screws on the chassis and PCBA. And separate PCBA from the chassis.
8. Disconnect the wire from the interface board.

9. Disconnect the LVDS from the interface board.
10. Release the screws on the hinge and bucket.

![Image of screws on hinge]

11. Remove the hinge POM.

![Image of hinge POM removed]

12. Tear the rubber foot from base.
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13. Separate the base plate and base cover.